

Shenzhen Star Instrument Co., Ltd.

Modular Transmitter Approval Request

Federal Communications Commission  
Equipment Authorization Division  
7435 Oakland Mills Road  
Columbia, MD 21046  
USA

**Company name:** Shenzhen Star Instrument Co., Ltd.  
**FCC ID:** 2A2X4MMJ051B015

Dear Sir/Madam,

In accordance with 47CFR 15.212 Modular Transmitters and KDB 996369 D01 'Module Equip Auth Guide v02'. FCC ID 2A2X4MMJ051B015 has been examined against the following requirements.

Requirement per 15.212 and KDB 996369 D01	Explanation from Grantee (do not write yes/no, but explain why product complies/how it is achieved)
The radio elements must have the radio frequency circuitry shielded. Physical components and tuning capacitor(s) may be located external to the shield, but must be on the module assembly.	The module have RF shield
The module must have buffered modulation/data inputs to ensure that the device will comply with Part 15 requirements with any type of input signal.	Module have buffered modulation/data inputs, and comply with FCC Part 15 requirements
The module must contain power supply regulation on the module.	Module have 3.3V DC power supply regulation
The module must contain a permanently attached antenna, or contain a unique antenna connector, and be marketed and operated only with specific antenna(s), per §§ 15.203, 15.204(b), 15.204(c), 15.212(a), 2.929(b).	Module have a PCB antenna, cannot remove
The module must demonstrate compliance in a stand-alone configuration.	Module demonstrate compliance in a stand-alone configuration
The module must be labeled with its permanently affixed FCC ID label, or use an electronic display (see KDB Publication 784748).	Module have a label and FCC ID
The module must comply with all specific rules applicable to the transmitter, including all the conditions provided in the integration instructions by the grantee.	Module comply with FCC Part15.247 requirements
The module must comply with RF exposure requirements	Module comply with RF exposure requirements

**Name:** Wenzhou Li

**Date:** 2021/9/8

**Title:** Product engineer

**Signature of applicant**

